


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F427IIT6	X01T*419XXX3	A	9991	2016-04-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	1650.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	24x24x1.4	176	L bend	
Comment	LQFP 176 24x24x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	X01T*419XXX3					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	21.182	mg	supplier	die	Silicon (Si)	7440-21-3		17.777	mg	839250	10774
Die or Dies					metallization	Aluminium (Al)	7429-90-5		0.082	mg	3871	50
Die or Dies					metallization	Copper (Cu)	7440-50-8		0.535	mg	25257	324
Die or Dies					metallization	Tantalum (Ta)	7440-25-7		2.301	mg	108630	1395
Die or Dies					metallization	Cobalt (Co)	7440-48-4		0.002	mg	94	1
Die or Dies					metallization	Tungsten (W)	7440-33-7		0.241	mg	11378	146
Die or Dies					passivation	Silicon Nitride (SiN)	68034-42-4		0.063	mg	2974	38
Die or Dies					passivation	Silicon Oxide(SiO2)	7631-86-9		0.181	mg	8545	110
Encapsulation	Other inorganic materials	938.546	mg	supplier	Molding Compound	Epoxy Resin A	Trade secret		41.840	mg	44580	25358
Encapsulation					Molding Compound	Epoxy Resin B	Trade secret		41.840	mg	44580	25358
Encapsulation					Molding Compound	Phenol Resin	Trade secret		62.760	mg	66869	38036
Encapsulation					Molding Compound	Carbon Black	1333-86-4		4.184	mg	4458	2536
Encapsulation					Molding Compound	Silica Fused	60676-86-0		787.922	mg	839513	477528
Leadframe	Other inorganic materials	666.052	mg	supplier	Alloy	Copper (CU)	7440-50-8		626.402	mg	940470	379638
Leadframe					Alloy	Nickel (Ni)	7440-02-0		24.780	mg	37204	15018
Leadframe					Alloy	Silicon (Si)	7440-21-3		5.370	mg	8062	3255
Leadframe					Alloy	Silver (Ag)	7440-22-4		8.260	mg	12401	5006
Leadframe					Alloy	Magnesium (Mg)	7439-95-4		1.240	mg	1862	752
Die Attach	Other inorganic materials	3.010	mg	supplier	Glue	Silver Flake	7440-22-4		2.330	mg	774086	1412
Die Attach					Glue	Epoxy Acylate	15625-89-5		0.150	mg	49834	91
Die Attach					Glue	Substiyuted Polyamine	68490-66-4		0.050	mg	16611	30
Die Attach					Glue	Bisphenol F	28064-14-4		0.300	mg	99668	182
Die Attach					Glue	2-Ethylhexyl glycidyl ether	2461-15-6		0.180	mg	59801	109
Bonding wire	Other inorganic materials	2.510	mg	supplier	Bonding wire	Au	7440-57-5		2.480	mg	988048	1503
Bonding wire					Bonding wire	Pd	7440-05-3		0.030	mg	11952	18
Finishing	Other inorganic materials	18.700	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		18.700	mg	1000000	11333